Product Qualification Report (PQR)

CY15V104QSN-108SXIT

Package: PG-DSO-8

All reliability stress tests according to JEDEC JESD 47 are assessed as PASS. The data outlined in this document may reference existing qualification results of similar products.

Table 1 Reliability stress tests

Test description	Abbr.	Condition	Duration	Min. # of Lots × sample size	Result
Accelerated lifetime simulation tests for device qualification					
High temperature operating life *JESD22-A108, JESD85*	HTOL	125°C Vmax	1000 h	3 × 77	Pass
Early life failure rate *JESD22-A108, JESD74*	ELFR	125°C Vmax	48 h	3 × 800	Pass
Non-volatile memory cycling endurance *JESD22-A117*	NVCE	Room and hot temperature	100 k	3 × 77	Pass
Data retention *JESD22-A117*	DR	Hot temperature	1000 h	3 × 77	Pass
Low temperature operating life *JESD22-A108*	LTOL	Covered by wafer technology qualification			Pass

Test description	Abbr.	Condition	Duration	Min. # of Lots × sample size	Result
Accelerated environment stress tests for devices in non-hermetic packages					
High temperature storage life *JESD22-A103*	HTSL	150°C	1000 h	3 × 25	Pass
Preconditioning *JESD22-A113, J-STD-20 (MSL)*	PC	MSL 3	3 × reflow 260°C	Before HAST, uHAST, TC	Pass
Highly accelerated temperature and humidity stress *JESD22-A110*	HAST	130°C 85% RH Vmax	96 h	3 × 25	Pass
Unbiased highly accelerated temperature and humidity stress *JESD22-A118*	UHAST	130°C 85% RH	96 h	3 × 25	Pass
Temperature cycling *JESD22-A104*	TC	-65°C to 150°C	500×	3 × 25	Pass

Test description	Abbr.	Comment	Result
Electrical verification tests			
Electrical parameter assessment	ED	test at room, hot, cold temperature	Pass
ESD human body model *JS-001*	ESD HBM	Class 2 (2000 V to < 4000 V)	Pass
ESD charged device model[1)] *JS-002*	ESD CDM	Class C2a (500 V to < 750 V)	Pass
Latch-up *JESD78*	LU	Class II.A	Pass

[1)] voltage refers to test condition (TC) mentioned in the standard

Test description	Abbr.	Comment	Result
Soft error rate *JEDEC JESD89-1 (un-accelerated)* *JEDEC JESD89-2/-3 (accelerated)*	SER	Covered by wafer technology qualification	Pass
Package assembly integrity tests for devices in non-hermetic packages			
Solder ball shear *JESD22-B117*	SBS	For Ball Grid Arrays (BGA) only	n.a
Wire bond pull *JESD22-B120*	BPS	Covered by package platform qualification and production monitoring	Pass
Bond shear *JESD22-B116*	BS	Covered by package platform qualification and production monitoring	Pass
Solderability *J-STD-002*	SD	Covered by package platform qualification and production monitoring	Pass
Tin whisker *JESD22-A121, requ. of JESD201*	WSR	Covered by package platform qualification and production monitoring	Pass

For further information and documentation please refer to the product homepage:
https://www.infineon.com/part/CY15V104QSN-108SXIT

Do you have a question about any aspect of this document?
Contact us: erratum@infineon.com

Trademarks
All referenced product or service names and trademarks are the property of their respective owners.

Edition 2026-01-01
Revision 3.01
Published by
Infineon Technologies AG
81726 Munich
Germany

© 2026 Infineon Technologies AG
and its affiliates. All rights reserved.

Public

Stay connected!

Scan QR code and explore offering
www.infineon.com

Important Notice

Products are sold or provided and delivered by Infineon Technologies AG and its affiliates ("Infineon") subject to the terms and conditions of the frame supply contract or other written agreement(s) executed by a customer and Infineon or, in the absence of the foregoing, the applicable Sales Conditions of Infineon.
General terms and conditions of a customer or deviations from applicable Sales Conditions of Infineon shall only be binding for Infineon if and to the extent Infineon has given its express written consent.

To the fullest extent permissible pursuant to applicable law, with respect to any information given in this document or in any associated documentation, Infineon disclaims all warranties and liabilities of any kind, whether express or implied, including but not limited to any warranties of merchantability, suitability of the products for the intended application or the specific use, or non-infringement of third-party rights.

Subject to the development and release of the products for series supply by Infineon, the technical specifications of the products are set forth in the relevant final datasheet provided by Infineon and, if any, agreed and signed specifications. Infineon's customers are required to evaluate the suitability of the products for the intended application or specific use.

The information given in this document is subject to change by Infineon at any time without notice.